



# KBMFxxSC6

A.S.D.™

## EMI FILTER AND LINE TERMINATION FOR PS/2 MOUSE OR KEYBOARD PORTS

### MAIN APPLICATION

EMI Filter and line termination for mouse and keyboard ports on:

- Desktop computers
- Notebooks
- Workstations
- Servers

### DESCRIPTION

On the implementation of computer systems, the radiated and conducted EMI should be kept within the required levels as stated by the FCC regulations. In addition to the requirements of EMC compatibility, the computing devices are required to tolerate ESD events and remain operational without user intervention.

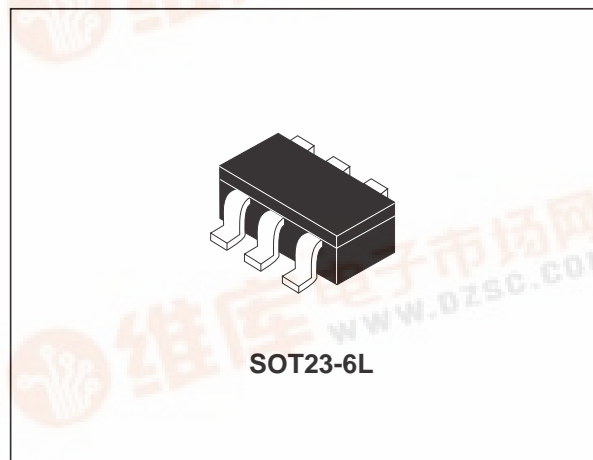
The KBMF implements a low pass filter to limit EMI levels and provide ESD protection which exceeds IEC 61000-4-2 level 4 standard. The device also implements the pull up resistors needed to bias the data and clock lines. The package is the SOT23-6L which is ideal for situations where board space is at a premium.

### FEATURES

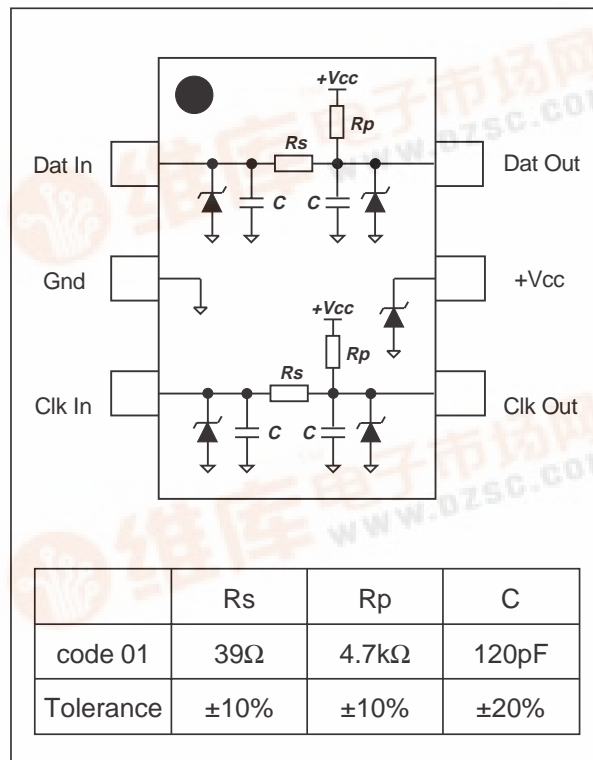
- Integrated low pass filters for Data and Clock lines
- Integrated ESD protection
- Integrated pull-up resistors
- Small package size
- Breakdown voltage:  $V_{BR} = 6V$  min

### BENEFITS

- EMI / RFI noise suppression
- ESD protection exceeding IEC61000-4-2 level 4
- High flexibility in the design of high density boards



### FUNCTIONAL DIAGRAM



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## KBMFxxSC6

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### COMPLIES WITH THE FOLLOWING ESD STANDARDS:

IEC 61000-4-2 (R = 330 $\Omega$  C = 150pF), level 4  
 $\pm 15$  kV (air discharge)  
 $\pm 8$  kV (contact discharge)

MIL STD 883C, Method 3015-6  
Class 3 C = 100 pF R = 1500  $\Omega$   
3 positive strikes and 3 negative strikes (F = 1 Hz)

### ABSOLUTE MAXIMUM RATINGS (T<sub>amb</sub> = 25°C)

| Symbol           | Parameter   | Value                | Unit     |
|------------------|---|----------------------|----------|
| V <sub>PP</sub>  | ESD discharge R = 330 $\Omega$ C = 150pF contact discharge<br>ESD discharge - MIL STD 883 - Method 3015-6 | $\pm 12$<br>$\pm 25$ | kV<br>kV |
| T <sub>j</sub>   | Junction temperature  | 150                  | °C       |
| T <sub>stg</sub> | Storage temperature range   | - 55 to +150         | °C       |
| T <sub>L</sub>   | Lead solder temperature (10 second duration)  | 260                  | °C       |
| T <sub>op</sub>  | Operating temperature Range   | 0 to 70              | °C       |
| P <sub>r</sub>   | Power rating per resistor   | 100                  | mW       |

### ELECTRICAL CHARACTERISTICS (T<sub>amb</sub> = 25°C)

| Symbol          | Parameters                 | Test conditions        | Min | Typ | Max | Unit    |
|-----------------|----------------------------|------------------------|-----|-----|-----|---------|
| I <sub>R</sub>  | Diode leakage current      | V <sub>RM</sub> = 5.0V |     |     | 10  | $\mu$ A |
| V <sub>BR</sub> | Diode breakdown voltage    | I <sub>R</sub> = 1mA   | 6   |     |     | V       |
| V <sub>F</sub>  | Diode forward voltage drop | I <sub>F</sub> = 50mA  |     | 0.9 |     | V       |

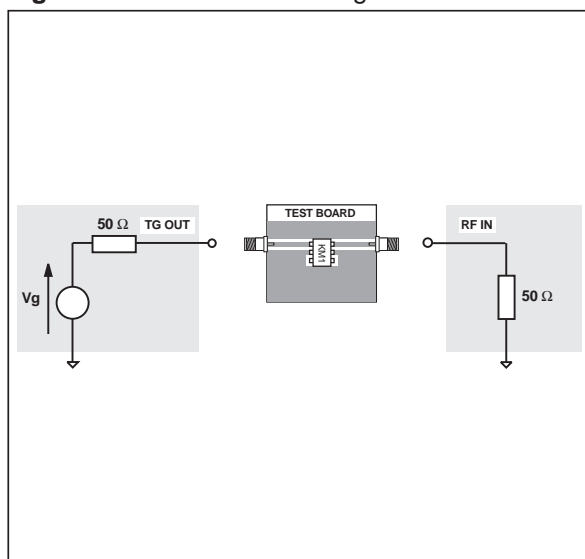
**TECHNICAL INFORMATION**

**EMI FILTERING**

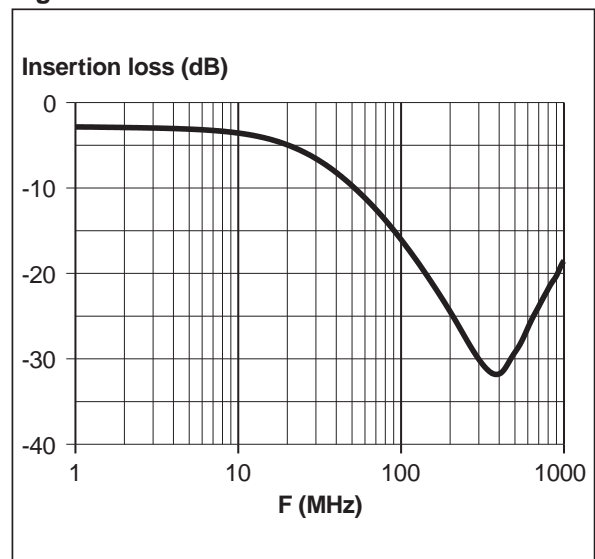
The KBMFxxSC6 ensure a filtering protection against ElectroMagnetic and RadioFrequency Interferences thanks to its low-pass filter structure. This filter is characterized by the following parameters :

- cut-off frequency
- Insertion loss
- high frequency rejection

**Fig. A1: Measurements configuration**



**Fig. A2: KBMFxxSC6 attenuation curve**



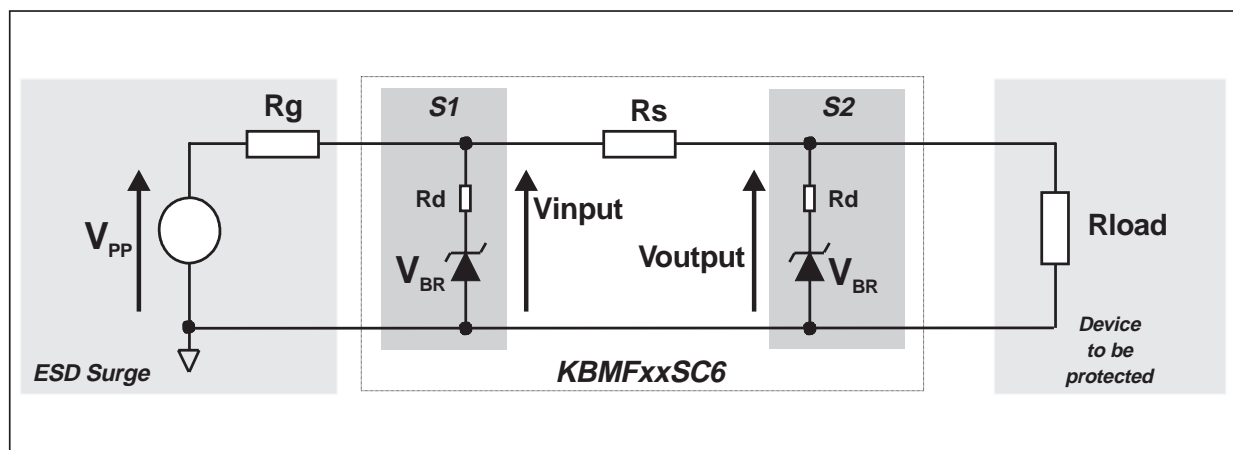
**ESD PROTECTION**

The KBMFxxSC6 is particularly optimized to perform ESD protection. ESD protection is based on the use of device which clamps at :

$$V_{output} = V_{BR} + R_d \cdot I_{PP}$$

This protection function is splitted in 2 stages. As shown in figure A3, the ESD strikes are clamped by the first stage S1 and then its remaining overvoltage is applied to the second stage through the resistor R. Such a configuration makes the output voltage very low at the Voutput level.

**Fig. A3: ESD clamping behavior**



## KBMFxxSC6

To have a good approximation of the remaining voltages at both  $V_{input}$  and  $V_{output}$  stages, we give the typical dynamical resistance value  $R_d$ . By taking into account these following hypothesis :  $R_t > R_d$ ,  $R_g > R_d$  and  $R_{load} > R_d$ , it gives these formulas:

$$V_{input} = \frac{R_g \cdot V_{BR} + R_d \cdot V_g}{R_g}$$

$$V_{output} = \frac{R_s \cdot V_{BR} + R_d \cdot V_{input}}{R_t}$$

The results of the calculation done for  $V_{PP}=8kV$ ,  $R_g=330\Omega$  (IEC 61000-4-2 standard),  $V_{br}=7V$  (typ.) and  $R_d = 1\Omega$  (typ.) give:

$$V_{input} = 31.2 \text{ V}$$

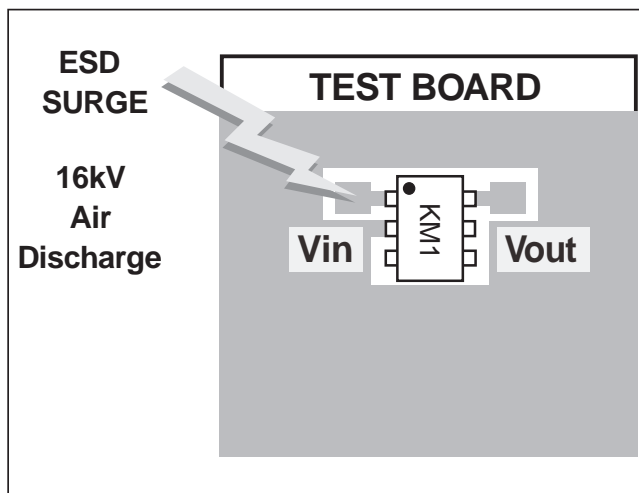
$$V_{output} = 7.8 \text{ V}$$

This confirms the very low remaining voltage across the device to be protected. It is also important to note that in this approximation the parasitic inductance effect was not taken into account. This could be few tenths of volts during few ns at the input side. This parasitic effect is not present at the output side due the low current involved after the resistance  $R_s$ .

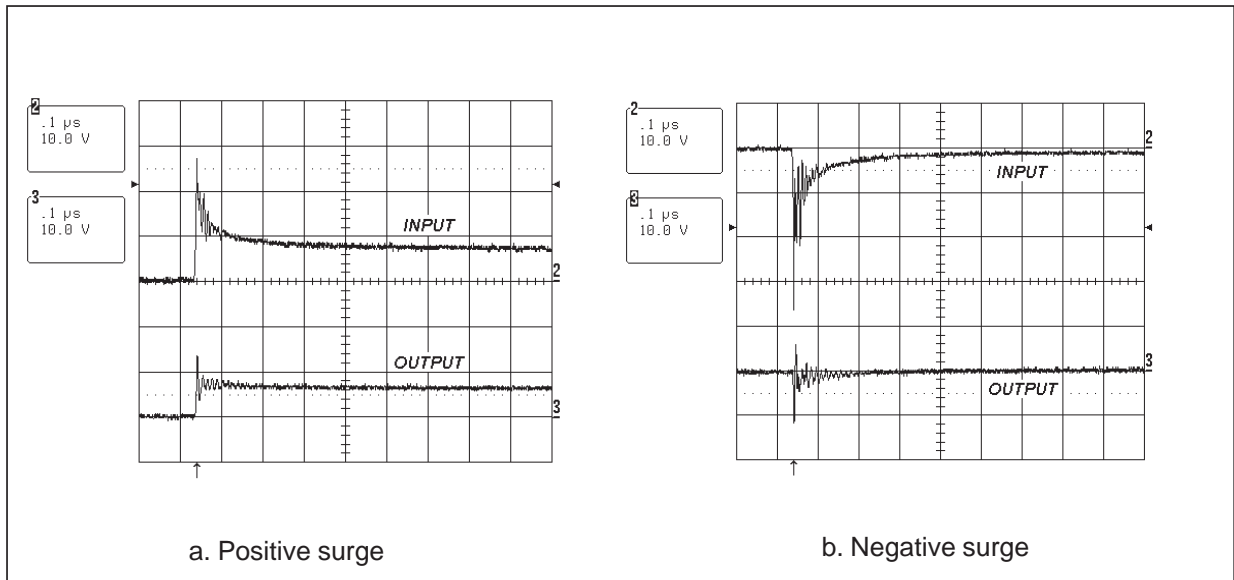
The measurements done here after show very clearly (Fig. A5) the high efficiency of the ESD protection :

- no influence of the parasitic inductances on output stage
- $V_{output}$  clamping voltage very close to  $V_{br}$  (positive strike) and  $-V_f$  (negative strike)

**Fig. A4:** Measurement conditions



**Fig. A5:** Remaining voltage at both stages S1 (Vinput) and S2 (Voutput) during ESD surge.



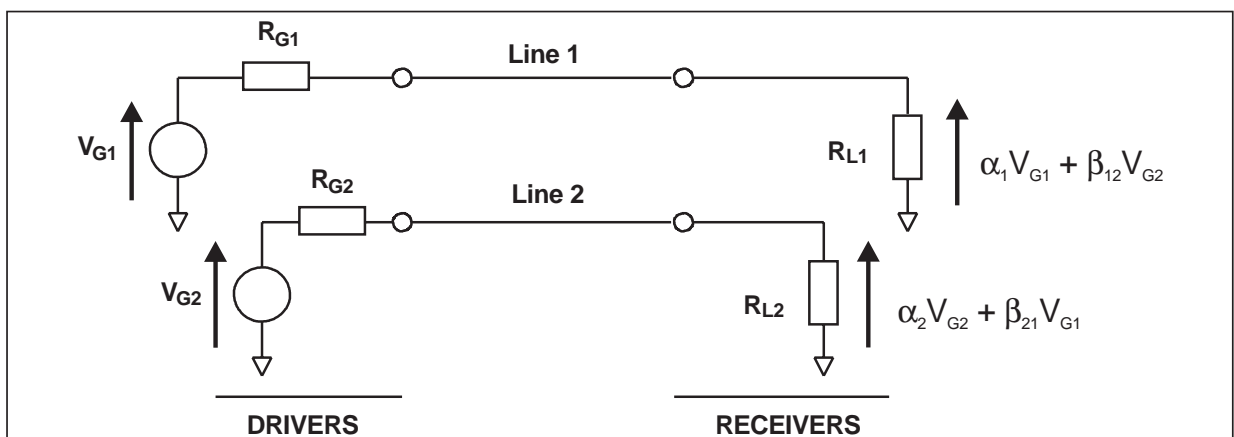
Please note that the KBMFxxSC6 is not only acting for positive ESD surges but also for negative ones. For these kind of disturbances it clamps close to ground voltage as shown in Fig. A5b.

**LATCH-UP PHENOMENA**

The early ageing and destruction of IC's is often due to latch-up phenomena which is mainly induced by dV/dt. Thanks to its structure, the KBMFxxSC6 provides a high immunity to latch-up phenomena by smoothing very fast edges.

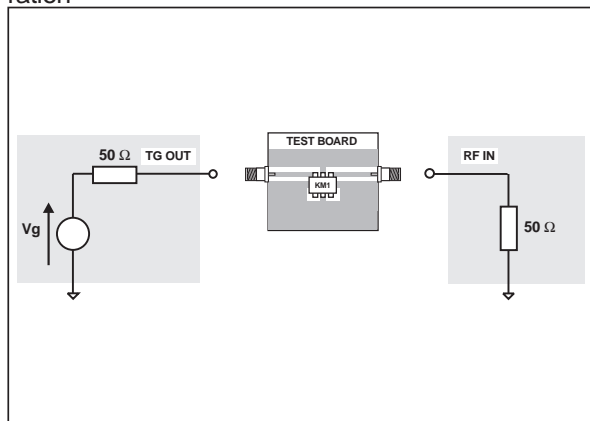
**CROSSTALK BEHAVIOR**

**Fig. A6:** Crosstalk phenomena



The crosstalk phenomena is due to the coupling between 2 lines. The coupling factor ( $\beta_{12}$  or  $\beta_{21}$ ) increases when the gap across lines decreases, this is the reason why we provide crosstalk measurements for monolithic device to guarantee negligible crosstalk between the lines. In the example above the expected signal on load  $R_{L2}$  is  $\alpha_2 V_{G2}$ , in fact the real voltage at this point has got an extra value  $\beta_{21} V_{G1}$ . This part of the  $V_{G1}$  signal represents the effect of the crosstalk phenomenon of the line 1 on the line 2. This phenomenon has to be taken into account when the drivers impose fast digital data or high frequency analog signals in the disturbing line. The perturbed line will be more affected if it works with low voltage signal or high load impedance (few  $k\Omega$ ).

**Fig. A7:** Analog Crosstalk measurements configuration



**Fig. A8:** Typical Analog Crosstalk measurement

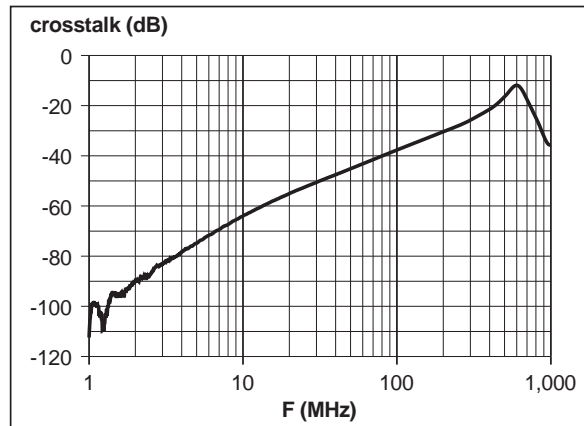
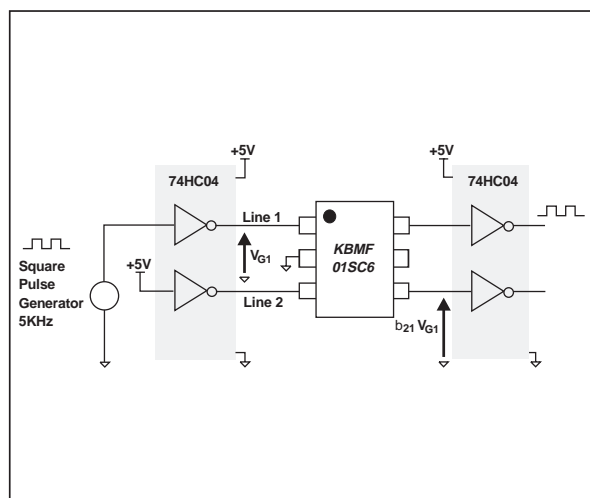


Figure A7 gives the measurement circuit for the analog crosstalk application. In figure A8, the curve shows the effect of the Data line on the CLK line. In usual frequency range of analog signals (up to 100MHz) the effect on disturbed line is less than -37dB.

**Fig. A9:** Digital crosstalk measurements configuration



**Fig. A10:** Digital crosstalk measurements

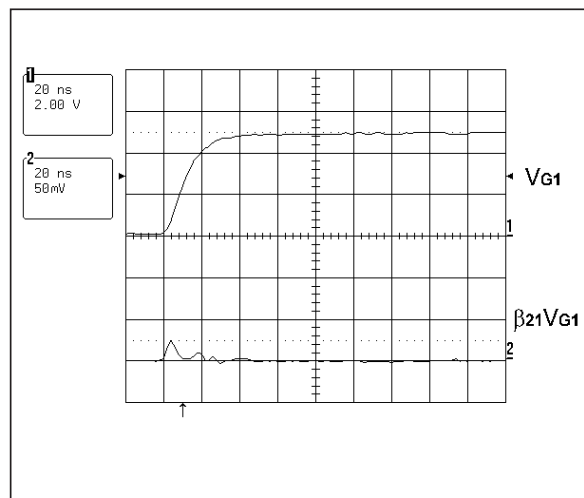
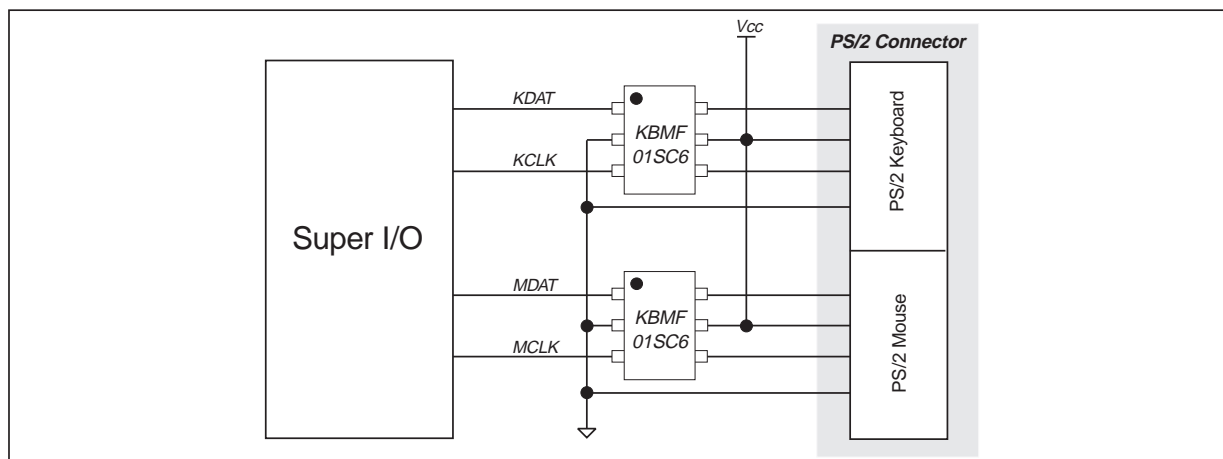


Figure A9 shows the measurement circuit used to quantify the crosstalk effect in a classical digital application.

Figure A10 shows that in such a condition signal from 0 to 5V and rise time of few ns, the impact on the other line is less than 50mV peak to peak. (Below the logic high threshold voltage). The measurements performed with falling edges gives the results within the same range.

## APPLICATION EXAMPLE

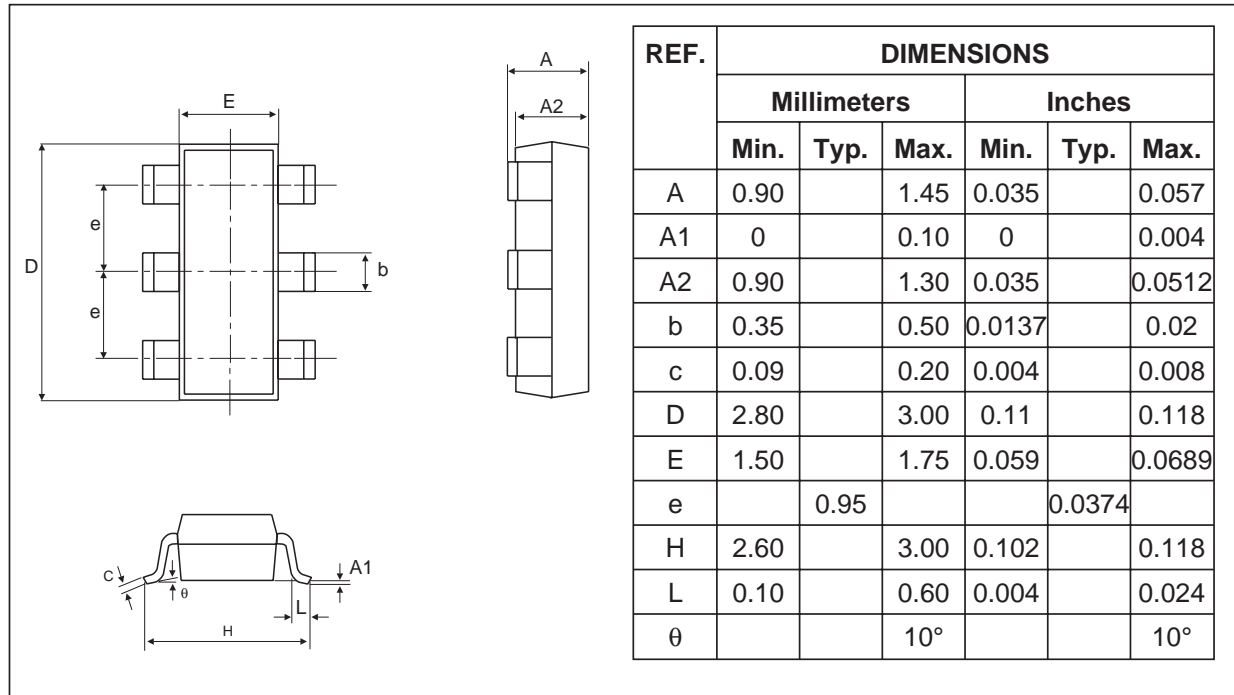
Fig. A11: Implementation of KBMFxxSC6 in a typical application



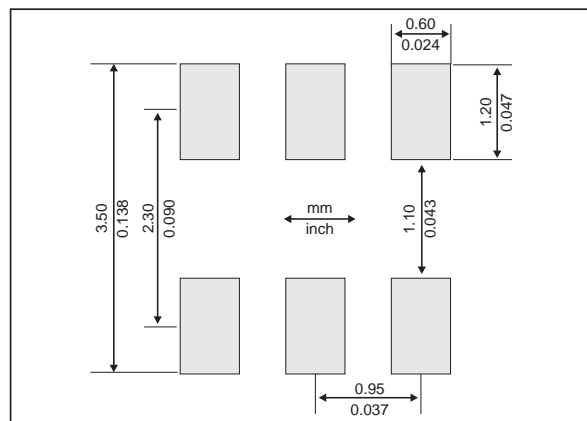
The KBMFxxSC6 device could be used on PS/2 mouse or keyboard as indicated by figure A11.

# KBMFxxSC6

## PACKAGE MECHANICAL DATA. SOT23-6L



### RECOMMENDED FOOTPRINT (mm)



### MECHANICAL SPECIFICATIONS

|                        |                           |
|------------------------|---------------------------|
| Lead plating           | Tin-lead                  |
| Lead plating thickness | 5µm min<br>25µm max       |
| Lead material          | Sn / Pb<br>(70% to 90%Sn) |
| Lead coplanarity       | 10µm max                  |
| Body material          | Molded epoxy              |
| Flammability           | UL94V-0                   |

### MARKING

| Type      | Order Code | Weight | Marking | Package  | Base Qty |
|-----------|------------|--------|---------|----------|----------|
| KBMF01SC6 | KBMF01SC6  | 16.7mg | KM1     | SOT23-6L | 3000     |

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